

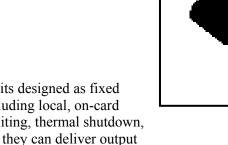
Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No. : 1/6

SOT-223

Three Terminal Positive Voltage Regulators

LM78D05L3



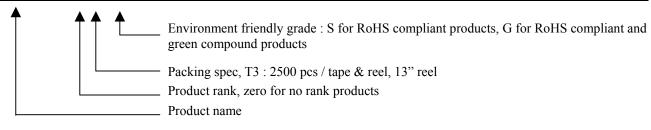
These voltage regulators are monolithic integrated circuits designed as fixed voltage regulators for a wide variety of applications including local, on-card regulation. These regulators employ internal current limiting, thermal shutdown, and safe-area compensation. With adequate heatsinking they can deliver output currents in excess of 1.0A. Although designed primarily as fixed voltage regulator, these devices can be used with external components to obtain adjustable voltages and currents.

Maximum Ratings

Rating	Symbol	Value	Unit
Input Voltage	VIN	35	V
Output Current	Io	1	A
Power Dissipation	PD	Internally Limited	W
Operating Junction Temperature Range	τJ	-40 to +125	°C
Storage Temperature Range	Tstg	-65 to +150	$^{\circ}\!\mathbb{C}$

Ordering Information

Device	Output Voltage	Package	Shipping
	Tolerance		
LM78D05L3-A-T3-G	± 3%	SOT-223 (Pb-free lead plating and	2500 mag/Tana & Daal
LM78D05L3-B-T3-G	± 5%	halogen-free package)	2500 pcs/Tape & Reel

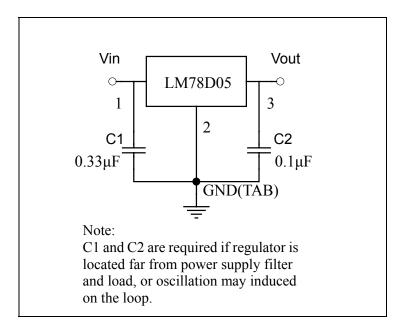




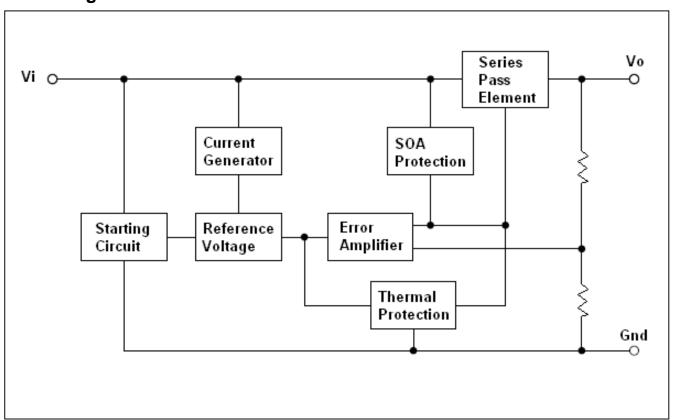
Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No. : 2/6

Typical Application Circuit



Block Diagram





Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No.: 3/6

Electrical Characteristics $V_{IN}=10V$, $I_{OUT}=500mA$, $T_{J}=25^{\circ}C$, $C_{IN}=0.33\mu F$, $C_{OUT}=0.1\mu F$, unless otherwise specified

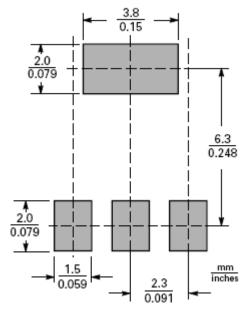
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Output Voltage						
LM78D05L3 A-rank	Vo		4.85	5.0	5.15	V
LM78D05L3 B-rank			4.75	5.0	5.25	
Output Voltage						
LM78D05L3 A-rank	Vo	5.0mA≤Iouт≤1.0A,PD≤15W	4.85	5.0	5.15	V
LM78D05L3 B-rank			4.75	5.0	5.25	
Line Regulation	ΔVo	7V≤V _{IN} ≤25V	-	-	50	mV
		8V≤V _{IN} ≤25V	-	-	25	
Load Regulation	$\Delta \mathrm{Vo}$	5.0mA≤Iouт≤1.5A	-	-	100	mV
_		250mA≤Iouт≤750mA	-	-	50	
Quiescent Current	IQ	Iouт≤1.0A	-	-	8	mA
Quiescent Current Change	$\Delta \mathrm{Iq}$	5.0mA≤Iouт≤1.5A	-	-	0.5	mA
		7V≤V _{IN} ≤25V	-	-	1.3	
Dropout Voltage	V_D	IOUT=1.0A	-	2	-	V
Peak Output Current	Ірк		1.7	-	-	A

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	Rth,j-c	15	°C/W
Thermal Resistance, Junction-to-ambient, max	Rth,j-a	80 (Note)	°C/W

Note: Surface mounted on a 1 in ² pad of 2 oz. copper, t≤10s; 120 °C/W when mounted on minimum copper pad.

Recommended soldering footprint

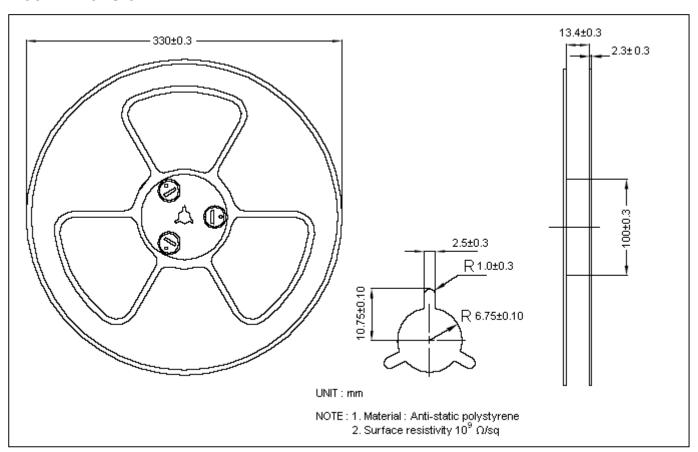




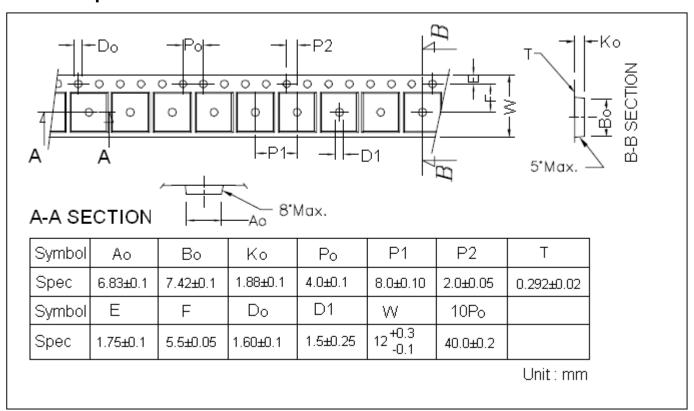
Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No. : 4/6

Reel Dimension



Carrier Tape Dimension





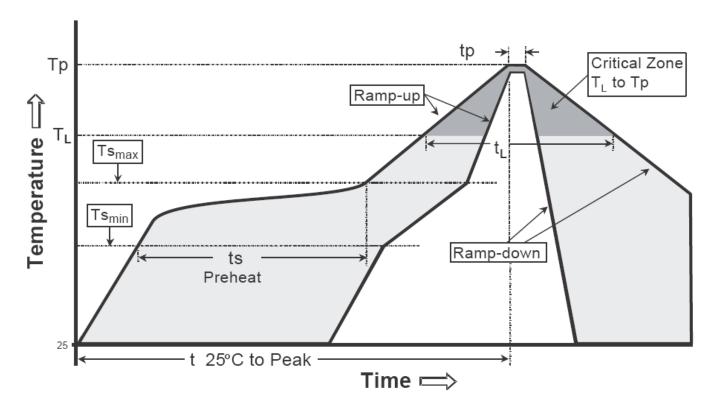
Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No. : 5/6

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time		
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds		

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly	
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.	
Preheat			
-Temperature Min(Ts min)	100°C	150°C	
-Temperature Max(Ts max)	150°C	200°C	
-Time(ts min to ts max)	60-120 seconds	60-180 seconds	
Time maintained above:			
-Temperature (T∟)	183°C	217°C	
– Time (t∟)	60-150 seconds	60-150 seconds	
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C	
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds	
Ramp down rate	6°C/second max.	6°C/second max.	
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.	

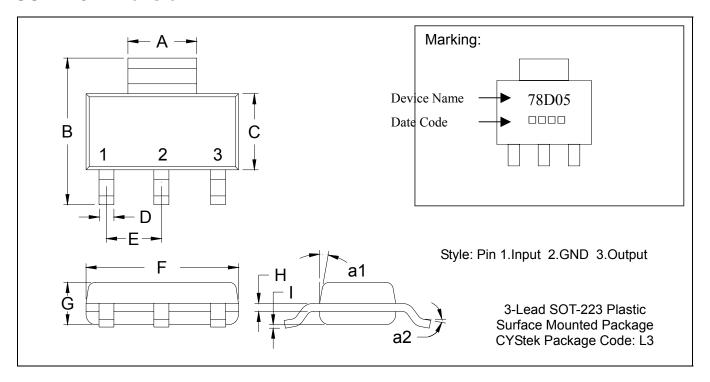
Note: All temperatures refer to topside of the package, measured on the package body surface.



Spec. No. : C511L3 Issued Date : 2008.03.19 Revised Date : 2016.01.28

Page No.: 6/6

SOT-223 Dimension



*: Typical

	: Typical									
DIM	Inches		Millim	Millimeters		Inches		Millimeters		
	Min.	Max.	Min.	Max.	DIM	Min.	Max.	Min.	Max.	
	Α	0.1142	0.1220	2.90	3.10	G	0.0551	0.0709	1.40	1.80
	В	0.2638	0.2874	6.70	7.30	Н	0.0098	0.0138	0.25	0.35
	С	0.1299	0.1457	3.30	3.70	I	0.0008	0.0039	0.02	0.10
	D	0.0236	0.0315	0.60	0.80	a1	*13°	-	*13°	-
	E	*0.0906	-	*2.30	-	a2	0°	10°	0°	10°
	F	0.2480	0.2638	6.30	6.70					

Notes: 1.Controlling dimension: millimeters.

- 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.